

9/-29-3

Sheet 1 of 2

FORM PTO-1449 (REV. 7-80)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. HIT 2 925-08	SERIAL NO. 10/671 618			
LIST OF DOCUMENTS CITED BY APPLICANT <i>(Use several sheets if necessary)</i>				APPLICANT J. TANAKA et al				
				FILING DATE 09/29/03		GROUP 2815		
U.S. PATENT DOCUMENTS								
* EXAMINER INITIAL	DOCUMENT	DATE	NAME	CLASS	SUBCLASS	FILING DATE (If Appropriate)		
nbe	AA	5,563,762	10/1996	Leung et al	1	1		
	AB	5,117,272	05-1992	Nomura et al				
	AC	5,310,863	05-1994	Sachdev				
	AD	6,071,755	06-2000	Baba et al				
	AE	6,106,906	08-2000	Matsuda et al				
	AF	5,296,716	03-1994	Ovashinsky et al				
	AG	4,132,823	1/2/79	Blackwell et al				
	AH	6,465,827	10/2002	Tanaka et al				
	AI							
	AJ							
AK								
FOREIGN PATENT DOCUMENTS								
	DOCUMENT	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION		
						YES	NO	
nbe	AL	8-124917	05-1996	Japan	1	1	<input type="checkbox"/>	<input type="checkbox"/>
	AM	7-278301	10-1995	Japan			<input type="checkbox"/>	<input type="checkbox"/>
	AN	07-221259	8/18/95	Japan			<input type="checkbox"/>	<input type="checkbox"/>
	AO	09-293837	11/11/97	Japan			<input type="checkbox"/>	<input type="checkbox"/>
	AP						<input type="checkbox"/>	<input type="checkbox"/>
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)								
nbe	AR	Lecture Collections in '96 Ferroelectric Film Memory Technique Forum, Science Forum, Inc., page 4-4, lines 1-12, Ishihara, January 26, 1996.						
nbe	AS	Epoxy Molding Compounds for Semiconductor Devices, Thermosetting Resins, Vol. 13, No. 4, page 37, right column, lines 8-23, Ogata et al, 1992.						
nbe	AT	Packaging Technique for Surface Mount Type LSI Packages and Improvements in Its Reliability, page 451, edited by Hitachi, Ltd.						
EXAMINER Jasmine Clark				DATE CONSIDERED 7/21/04				
<small>* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</small>								

9-29-3

Sheet 2 of 2

FORM PTO-1449 (REV. 7-80)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. HIT 2 925-08		SERIAL NO. 10/671,618		
LIST OF DOCUMENTS CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT J. TANAKA et al				
				FILING DATE 09/29/03		GROUP 2815		
U.S. PATENT DOCUMENTS								
* EXAMINER INITIAL		DOCUMENT	DATE	NAME	CLASS	SUBCLASS	FILING DATE (If Appropriate)	
	AA							
	AB							
	AC							
	AD							
	AE							
	AF							
	AG							
	AH							
	AI							
	AJ							
	AK							
FOREIGN PATENT DOCUMENTS								
		DOCUMENT	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO	
	AL						<input type="checkbox"/>	<input type="checkbox"/>
	AM						<input type="checkbox"/>	<input type="checkbox"/>
	AN						<input type="checkbox"/>	<input type="checkbox"/>
	AO						<input type="checkbox"/>	<input type="checkbox"/>
	AP						<input type="checkbox"/>	<input type="checkbox"/>
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)								
gbe	AR		A Study of Package Cracking During the Reflow Soldering Process, "A" Edition, Vol. 55, No. 510, Kitano et al, 1989-2.					
gbe	AS		Effects of Mold Compound Properties on Lead-on-Chip (LOC) Package Reliability During IR Reflow, 1996 Electronic Components and Technology Conference, Yang et al.					
	AT							
EXAMINER Jasmine Clark				DATE CONSIDERED 7/21/04				
* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.								

11-14-3

Sheet 1 of 1

FORM PTO-1449
(REV. 7-80)U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
HIT 2 925-08SERIAL NO.
10/671,681LIST OF DOCUMENTS CITED BY APPLICANT
(Use several sheets if necessary)APPLICANT
J. Tanaka et alFILING DATE
9/29/03GROUP
2815

U.S. PATENT DOCUMENTS

* EXAMINER INITIAL		DOCUMENT	DATE	NAME	CLASS	SUBCLASS	FILING DATE (If Appropriate)
ybe	AA	5,068,712	11/1991	Murakami			
	AB	5,272,247	12/1993	Sotokawa			
	AC	5,536,584	07/1996	Sotokawa			
ybe	AD	6,147,374	11/2000	Tanaka			
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

FOREIGN PATENT DOCUMENTS

		DOCUMENT	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
ybe	AL	11-233738	08/1999	Kumagi			<input type="checkbox"/>	<input type="checkbox"/>
ybe	AM	5-112644	05/1993	Shoji			<input type="checkbox"/>	<input type="checkbox"/>
	AN						<input type="checkbox"/>	<input type="checkbox"/>
	AO						<input type="checkbox"/>	<input type="checkbox"/>
	AP						<input type="checkbox"/>	<input type="checkbox"/>

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

	AR		
	AS		
	AT		

EXAMINER

Jasmine Clark

DATE CONSIDERED

7/21/04

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.